

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	
Son K. Quan et al.	Examiner: Unknown
Application No.: To be assigned - A Continuation of Application No. 09/062,986 filed April 20, 1998	Group Art Unit: Unknown
Filed: Concurrently Herewith	Docket No: SC09785TCD1
Title: SEMICONDUCTOR PACKAGE AND METHOD THEREFOR	

Commissioner for Patents
Box Patent Application
Washington, DC 20231

PRELIMINARY AMENDMENT

Dear Commissioner:

Please amend the current Application as set forth below.

REPLACEMENT PARAGRAPHS

On page 1, after the title and before the “Background of the Invention”, please insert the following new paragrah:

“This application is a continuation of prior US patent application Serial Number 09//062,986 filed April 20, 1998, which is a divisional application of US Serial Number 08/708296 filed on September 4, 1996.”

REPLACEMENT CLAIMS

Please cancel claims 1-13.

Please add the following claims 14-22.

14. (New Claim) A semiconductor package array comprising:
an interconnect substrate having a plurality of substantially identical package sites arranged in an array, the plurality of sites being separated by a singulation space;
a semiconductor device mounted within each site and interconnected thereto;
and
a single and continuous overmolded encapsulant material which encapsulates each semiconductor device, the plurality of sites, and the singulation space.
15. (New Claim) The semiconductor package array of claim 14 wherein a top surface of the overmolded encapsulant material has a surface deviation of less than 0.13 millimeters across a length of the encapsulant material.
16. (New Claim) The semiconductor package array of claim 14 wherein the plurality of package sites are arranged in an array of at least four by four package sites.
17. (New Claim) A method for making a packaged semiconductor device comprising:
providing an interconnect substrate having a plurality of substantially identical package sites arranged in an array, the plurality of sites being separated by a singulation space;
mounting and interconnecting a semiconductor device within each site; and
overmolding a single and continuous encapsulant over each semiconductor device, the plurality of sites, and the singulation space.
18. (New Claim) The method of claim 17 wherein overmolding produces a top surface of the encapsulant which has a surface deviation of less than 0.13 millimeters across a length of the encapsulant.
19. (New Claim) The method of claim 17 wherein providing an interconnect substrate comprises providing an interconnect substrate wherein the plurality of package sites are arranged in an array of at least four by four package sites.
20. (New Claim) The method of claim 17 further comprising the step of singulating the plurality of package sites after overmolding.

21. (New Claim) The method of claim 20 wherein singulating comprises sawing through the single and continuous encapsulant and the interconnect substrate along the singulation space.

22. (New Claim) The method of claim 20 wherein singulating produces a plurality of packaged semiconductor devices, and further comprising the step of handling each packaged semiconductor device with automated pick and place equipment.

REMARKS

This Preliminary Amendment is being submitted together with the filing of a continuation application under 37 CFR 1.53b. The present application is to be filed as a continuation of co-pending patent application U.S. Serial Number 09/062,986 filed on April 20, 1998. With amendments presented herein, Applicants are canceling original claims 1-13 and adding new claims 14-22. The newly added claims are fully supported by the application as originally filed, and are believed to be patentable over the prior art cited in each of the preceding related applications (copies of which are herein provided together with PTO-1449).

Applicant believes the application is in condition for allowance which action is respectfully solicited. Please contact Applicants attorney identified below if there are any issues regarding this communication or the current Application.

Aug 13, 2001.
Date

Respectfully submitted,



Patricia S. Goddard

Attorney for Applicants

Registration No. 35,160

Customer No. 23125

Telephone No. (512) 996-6839

Facsimile No. (512) 996-6854